Expertise Applied | Answers Delivered


## Applications

- Smartphones and Tablets
- Notebook PC
- e-Readers
- Portable medical equipment
- Mobile point of sale
- Wearables
- Smartwatches
- Wireless speakers
- Portable game players


## Description

Littelfuse zeptoSMDC Series PPTC is developed for overcurrent and overtemperature protection in mobile applications. It works as a 'fail-safe' to protect battery management ICs and fuel gauges.

## Features

- Maximum electrical
- Small footprint 0201 size
- RoHS compliant
- Short circuit current: 82~200mA
- ISO/TS 16949 certified


## Benefits

- Resets to normal operation after fault is
- Save space due to small footprint cleared
- Help protect battery monitor IC from electrical over-stress


## Electrical Characteristics

| Part Number | Initial Resistance Ohms @ $25^{\circ} \mathrm{C}$ |  | $\begin{aligned} & V_{\text {max }}{ }^{2} \\ & (\mathrm{Vdc}) \end{aligned}$ | $\begin{aligned} & I_{\text {max }}{ }^{3} \\ & (\mathrm{~mA}) \end{aligned}$ | $\begin{array}{\|l} \text { Trip } \\ \text { Temperature } \\ { }^{\circ} \mathrm{C} \\ \text { TYP } \end{array}$ |  | Time to Trip ${ }^{5}$ |  | Post Process Resistance ${ }^{6}$ |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | Min ${ }^{1}$ | Max |  |  |  |  | Current (mA) | Time (ms) <br> Max | ohms <br> @ $-20^{\circ} \mathrm{C}$ <br> Min | ohms <br> @ $60^{\circ} \mathrm{C}$ <br> Max |
| zeptoSMDC0011F | 10 | 80 | 13 | 82 | 125 | 11 | 80 | 20 | 68 | 290 |
| zeptoSMDC0015F | 10 | 60 | 13 | 200 | 125 | 15 | 80 | 20 | 28 | 150 |

## Notes:

1. $R_{\text {min }}=$ Minimum resistance of device in initial (un-soldered) state
2. $\mathrm{V}_{\max }=$ Maximum voltage device can withstand without damage at rated current $\left(I_{\max }\right)$
3. $I_{\max }=$ Maximum fault current device can withstand without damage at rated voltage $\left(\mathrm{V}_{\max }\right)$
4. $I_{\text {hold }}=$ Hold current: maximum current device will pass without tripping in $25^{\circ} \mathrm{C}$ still air. Values specified using PCB's with $0.004^{\prime \prime} \times 1.0$ ounce copper traces
5. Time to trip values specified using PCB's with $0.004^{\prime \prime} \times 1.0$ ounce copper traces
6. With LOCTITE ECCOBOND UF 3915 , curing condition: $140^{\circ} \mathrm{C} / 20 \mathrm{mins}$, resistance is measured 12 hours post coating curing process

POLYSWITCH ${ }^{\oplus}$
Surface Mount > zeptoSMDC

## Environmental Specifications

| Operating Temperature | $-20^{\circ} \mathrm{C}$ to $60^{\circ} \mathrm{C}$ |
| :--- | :--- |
| Passive Aging | $+85^{\circ} \mathrm{C}, 1000$ hours <br> $-25 \%$ typical resistance change |
| Humidity Aging | $-65^{\circ} \mathrm{C}, 90 \%$ R.H., 100 hours <br> $-1+15 \%$ typical resistance change |
| Thermal Shock | MIL-STD-202, Method 107G <br> $-33 \%$ typical resistance change <br> $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ (20 Times) |
| Vibration | MIL-STD-202, Method 204, <br> Condition A No change |
| Moisture Sensitivity Level | Level 2a, J-STD-020 |

## Physical Specifications

| Terminal Materials | Solder-Plated Copper <br> (Solder Material: NiAu) |
| :--- | :--- |
| Lead Solderability | Meets EIA Specification RS186-9E, <br> ANSI/J- STD-002B, Test S |

Soldering Parameters

| Profile Feature |  | Pb-free assembly |
| :---: | :---: | :---: |
| Average Ramp-Up Rate (Liquidus Temp ( $\mathrm{T}_{\mathrm{L}}$ ) to peak |  | $1 \sim 3^{\circ} \mathrm{C} /$ second max. |
| Preheat | Temperature Min. ( $\mathbf{s s}_{\text {min }}$ ) | $130^{\circ} \mathrm{C}$ |
|  | Temperature Max. ( $\mathrm{Ts}_{\text {max }}$ ) | $180^{\circ} \mathrm{C}$ |
|  | Time Min. to Max. (Ts) | 90-110 seconds |
| $\mathrm{Ts}_{\text {max }}$ to $\mathrm{T}_{\mathrm{L}}$ Ramp-up Rate |  | $\leq 2^{\circ} \mathrm{C} /$ seconds max. |
| Reflow | Temperature ( $\mathrm{T}_{\mathrm{L}}$ ) (Liquidus) | $217^{\circ} \mathrm{C}$ |
|  | Time ( $\mathrm{t}_{\mathrm{L}}$ ) | 60~70 seconds |
| Peak Temperature ( $\mathrm{T}_{\mathrm{p}}$ ) |  | $240^{\circ} \mathrm{C}$ |
| Time within $3^{\circ} \mathrm{C}$ of actual Peak Temperature ( $\mathrm{t}_{\mathrm{p}}$ ) |  | 35 seconds |
| Ramp-Down Rate |  | 2~4* ${ }^{\circ} \mathrm{C}$ seconds |
| Time $25^{\circ} \mathrm{C}$ to Peak Temperature ( $\mathrm{T}_{\mathrm{p}}$ ) |  | 300 seconds max. |



- All temperature refer to topside of the package, measured on the package body surface.
- If reflow temperature exceeds the recommended profile, devices may not meet the performance requirements.
- Recommended reflow methods:IR, vapor phase oven, hot air oven.
- Customer should validate that the solder paste amount and reflow recommendations to meet its application
- Recommended maximum paste thickness is $0.25 \mathrm{~mm}(0.010 \mathrm{inch})$
- Devices can be cleaned using standard industry methods and aqueous solvents.
- Devices can be reworked using the standard industry practices (avoid contact to the device).


## Physical Dimension



## Solder Pad Layout



| Part Number | A |  | B |  | C |  | D |  |
| :--- | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | Min | Max | Min | Max | Min | Max | Min | Max |
| zeptoSMDC0011F | 0.55 | 0.65 | - | 0.40 | 0.40 | 0.50 | 0.10 | 0.25 |
|  | $(0.022)$ | $(0.026)$ | - | $(0.016)$ | $(0.016)$ | $(0.020)$ | $(0.004)$ | $(0.010)$ |
| zeptoSMDC0015F | 0.55 | 0.65 |  | 0.40 | 0.40 | 0.50 | 0.10 | 0.25 |

## Packaging

| Part Number | Ordering | Tape \& Reel Quantity | Minimum Orgder Quantity | Recommneded Pad Layout Figures [mm(in)] |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Dimension A (Nom) | Dimension B (Nom) | Dimension C (Nom) |
| zeptoSMDC0011F | RF5005-000 | 15,000 | 15,000 | $\begin{gathered} 0.45 \\ (0.0178) \end{gathered}$ | $\begin{gathered} 0.325 \\ (0.013) \end{gathered}$ | $\begin{gathered} 0.250 \\ (0.010) \end{gathered}$ |
| zeptoSMDC0015F | RF5006-000 | 15,000 | 15,000 | $\begin{gathered} 0.45 \\ (0.0178) \end{gathered}$ | $\begin{gathered} 0.325 \\ (0.013) \end{gathered}$ | $\begin{gathered} 0.250 \\ (0.010) \end{gathered}$ |

Part Numbering System


## Warning

- Electrical performance of the device can differ according to installation conditions. Users should independently evaluate the suitability of the device under the actual application conditions.
- Operation beyond maximum ratings may result in device damage.
- Exposure to silicon-based oils, solvents, electrolytes, acids, or similar materials can adversely affect device performance.
- The device undergoes thermal expansion during fault conditions. It should be provided with adequate space to allow expansion and should be protected against mechanical stress.
- Consult with Littelfuse if the device will experience thermal process other than reflow onto PCB board, such as molding or hand soldering.

Tape and Reel Specifications



Standard Pack Quantity: 15,000 pcs Minimum Order Quantity: 15,000 pcs


| All dimensions in mm |  |
| :--- | :--- |
| $\mathbf{W}$ | $8 \pm 0.1$ |
| $\mathbf{P}_{0}$ | $4 \pm 0.1$ |
| $\mathbf{P}_{1}$ | $2 \pm 0.05$ |
| $\mathbf{P}_{\mathbf{2}}$ | $2 \pm 0.05$ |
| $\mathbf{A}_{0}$ | $0.53 \pm 0.03$ |
| $\mathbf{B}_{0}$ | $0.70 \pm 0.03$ |
| $\mathbf{D}_{0}$ | $1.55 \pm 0.05$ |
| $\mathbf{F}$ | $3.5 \pm 0.05$ |
| $\mathbf{E}$ | $1.75 \pm 0.05$ |
| $\mathbf{T}$ | $0.42 \pm 0.03$ |
| $\mathbf{A}$ | $178.0 \pm 1.0$ |
| $\mathbf{N}$ | $54.0 \pm 0.5$ |
| $\mathbf{W}_{1}$ | $9.5 \pm 0.5$ |
| $\mathbf{W}_{2 \text { max }}$ | 15.0 |

Disclaimer Notice - Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at www.littelfuse.com/disclaimer-electronics.

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